



- NOTES :
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE : 0.125 OHM MAX. AT PIN NO.1
OTHER LESS THAN 0.7 OHM MAX.

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						48 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	M.K	K.M		DEC.18.'78
						SCALE 10 / 1	MATERIAL AS INDICATED				
							THIRD ANGLE PROJECTION				
△	REDRAWN : CONVERTED CAD DATA	Y.M	H.S/S.F	T.A	JAN.21.'98		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.			SHEET
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			KD-S78527-F	2 / 2		